

Ultrasonic Laserbonder M17LSB

F & K DELVOTEC - Partner for Tomorrow's Interconnection Technology.

Developed in close co-operation with Fraunhofer Institute for Laser Technology in Aachen, the combination of ultrasonic bonding and laser welding offers the best of both worlds. It is ideal for package interconnects in power modules and for battery pack assembly. Aluminium, copper or nickel ribbons are welded by laser energy at low bond forces. The process offers a larger range of choice in very diverse joining materials, compared to ultrasonic bonding. As a further advantage, it is very easy to automate.



Advantages

- The best of both worlds:
 Combination of laser welding and wire bonding
- Higher current carrying capability with larger connector cross sections compared to ultrasonic wire bonding
- Lowers manufacturing costs through reduced demands on the surface quality of the parts to be connected
- Allows XYZ positional tolerance compared to laser welding through use of touch down sensor and pattern recognition
- No damage to parts because of lower clamping forces in the work holder
- Combines three processes in a single machine without modification:
 - Laser bonding of ribbon
 - Laser-tab-bonding of connections
 - LIMBO



NOT JUST MACHINES.
BUT BONDING SOLUTIONS.

MADE FOR YOU - YOUR ADVANTAGES AT A GLANCE









500 W

- · CW infrared
- · Power modulation
- · PCB connections
- Al/Cu ribbon thickness 100 µm

600 W

- · CW infrared
- Power modulation
- DCB connections
- · Terminal connections
- Al/Cu ribbon thickness 200 µm

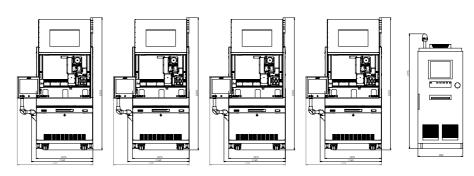
700 W

- · CW infrared
- · Power modulation
- · DCB, steel, die-cast Al
- · Terminal connections
- Al/Cu/Ni ribbon thickness up to 400 µm

1,000 W

- · CW infrared
- · Power modulation
- TAB Bonding up to 800 µm thickness
- Suitable for battery pack connections
- AI/Cu/Ni ribbon thickness up to 500 μm

ULTRASONIC LASERBONDER MACHINE MODEL



M17LSB	500 W	600 W	700 W	1,000 W	Laser Unit
X-axis	595 mm (23.5")	595 mm (23.5")	595 mm (23.5")	595 mm (23.5")	
Y-axis	340 mm (13.4")	340 mm (13.4")	340 mm (13.4")	340 mm (13.4")	
Z-axis	100 mm (4")	100 mm (4")	100 mm (4")	100 mm (4")	
Width	1,073 mm	1,073 mm	1,073 mm	1,073 mm	850 mm
Height with/without signal lamp	2,501 / 1,975 mm	2,501 / 1,975 mm	2,501 / 1,975 mm	2,501 / 1,975 mm	2,175 mm / -
Depth	1,565 mm	1,565 mm	1,565 mm	1,565 mm	1,200 mm
Weight	1,100 kg	1,100 kg	1,100 kg	1,100 kg	510 kg
Working height	SMEMA compliant 850-1,050 mm				
Power supply	3P / 200 V / 208 V / 230 V / 400 V / PE; 50 Hz / 60 Hz				
Compressed air	4-8 bar				
Vacuum connection	< -0.8 bar				
Optional	Supply for water-water cooler, purging gas for N2				



• Ribbon materials Al, Au, Ag, Ptlr, Pt, Cu, Ni

· Ribbon dimensions

- Max. cross sections up to 5,000 µm x 500 µm
- Min. cross sections down to 500 μm x 100 μm
- Customer specific dimensions on request

Joining materials

- Al, die-cast Al, Cu, Ni, brass, bronze, steel
- Other metals on request

· Ribbon spool

- Spool diameter 3", 3,5", 4"
- Larger diameters optional
- Automatic ribbon feed
- Detection of ribbon end by CCD sensor

Cutting process

Active, programmable cut depth, front cut

· Bond tool

Special tools of length 50 mm, 60 mm, 70 mm, 90 mm, 100 mm & 110 mm

· Touchdown sensor

- Inductive sensor with linear working range
- Anti-crash hardware sensor

Laser power

500 W, 600 W, 700 W, 1,000 W (each freely adjustable between 10 and 100 %)

Optics variants

- Optics for tools 50 to 70 mm
- Optics for tools 90 to 110 mm for extreme cavity depth

· Adaptation to tool lengths

Tracking of laser focus position for different tool lengths and varying touchdown speeds

Focus spot diameter

 $<50~\mu m$ for tool length 60 mm and 100 mm, resp.

• Beam quality M²

≤ 1.5

· Laser beam source

CW fibre laser with fundamental mode radiation

Speed

- Speed up to 1 wire/sec (depending on application)
- Welding time depending on ribbon width and the desired connection area
- Simple scale-up of connection area possible

ULIF

ULTRASONIC LASERBONDER MACHINE MODEL



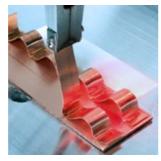




MACHINE BASE

X-Y-axes	Linear encoder resolution better than 0.1 µm	
P-axis	+/- 180° AC servomotor with absolute encoder, resolution 0.0035°	
Z-axis	Up to 100 mm, AC servomotor with absolute encoder, resolution 0.5 μm	
Positional accuracy	$<+/-5~\mu m$ @ 3 sigma, incl. PRU/Wire/Tool/Application	
Repeatability on the product	< +/-3 µm @ 3 sigma, incl. PRU/Wire/Tool/Application	
Working height	According to SMEMA 850-1,050 mm	
Monitor	21" flat screen	
Certification	SEMI S2, CE, Laser Unit Class 1 according to EN 60825-1:2014	
Connections	SMEMA, USB, RJ 45, Digital I/O	
Operating system	Real-time, Unix®-based multi-tasking OS	
Pattern recognition unit	Cognex® PatMax® System	
Recognition time	Up to 2 ms per pattern recognition	
Alignment correction	NEW Flexsearch, single point recognition incl. phase angle, two point recognition, phase angle correction $\pm -5\%$	
Precision	Sub-pixel resolution down to 0.1 pixel	
Camera	Moving CCD-camera, 640 x 480 pixel	
Resolution	Standard approx. 30 µm per pixel, adjustable using different optics	
Image size	Standard 19.2 x 14.4 mm, adjustable using different optics	
Illumination	Ring light, red, blue, white	
Manual work stations	From standard size for PCB 4" \times 4", 6" \times 6", 8" \times 6", 10" \times 6", 10" \times 8" up to 650 mm \times 350 mm (25" \times 14"), vacuum and $/$ or mechanical clamping	
Automatic parts handling	Belt indexer for flat substrates, e. g. ceramic substrates, PCB or workpiece carriers, substrate length: flexible, according to requirements; substrate width up to 350 mm	
Network connectivity	TCP/IP/FTP data exchange, SMEMA for in-line connections to other machines, SEMI communication standard SECS/GEM, MES host connectivity	







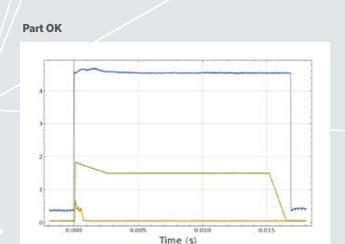


NOT JUST MACHINES. BUT BONDING SOLUTIONS.

QUALITY TOOLS

Laser quality monitoring

The laserbonder can be equipped with a process control system which permits real-time monitoring of standard welding processes. It supplies quality data on every single bond by detecting deviations from the programmed welding parameters as well as process fluctuations. The welding process is compared to characteristic references which are a composite of various signals, automatically supporting the user when deciding about OK or NOK classifications for the joint.





Further information about the system is available upon request.

Laser adjustment kit

- Camera system and PRU for easy adjustment and checking the bond tool
- Software based adjustment of laser beam relative to the bond tool and tuning of the focus position
- Graphical display of the target position of bond tool and cutter
- Minimal adjustment time when changing bond tool and cutter
- Detection of tool contamination and prevention of faults

Traceability

- Connection of standard F & K or customized MES
- · Connection to existing host system
- Storing, retrieving and transferring process settings per wire
- · Parts traceability by barcode or RFID
- · SECS/GEM state monitoring

Barcode & DMC-Reader

- Fully automatic part recognition, recipe and process data assignment
- Available as flexible hand-held DMCreader or fixed-position integrated unit

Expanding process limits by

- Combination of CW micro and oscillation welding
- Excellent beam quality and high dynamic range of beam motion for improved weld seam strength
- Optimal adaptation of connection area between ribbon and substrate
- Welding depth and seam width independently adjustable
- Flexible laser power modulation for varying requirements in amplitude and frequency
- Optimal quality monitoring

BOND ACADEMY: your advantages?

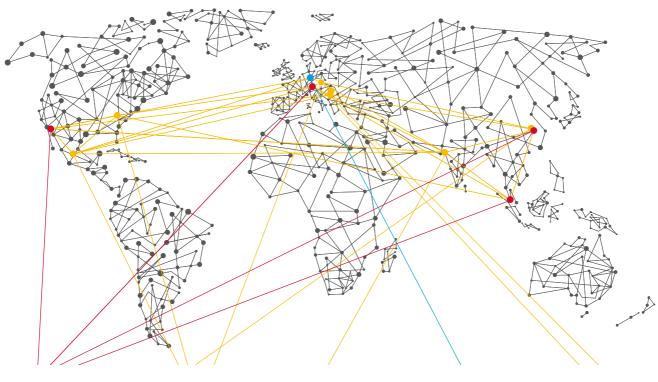
Our support for implementing your requirements and optimising your processes:

- · Competent advice
- Determining the correct transducer frequency for the application
- Rapid prototyping
- · Validation of product design
- Sample bond tests and pilot series manufacture
- · Training your service technicians
- · Ramp-up-support



POWERFUL SYNERGIES AS "MEMBER OF STRAMA GROUP"

Together with our parent company, Strama-MPS, we integrate our wirebonders into complete assembly lines with other joining, assembling and testing stations. Our customers profit from the combination of our bonding and automotive expertise, "One-stop-shopping", and the interface free quality of the complete package.





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